



2V <= Vin <= 5.25V
 Vstart = 3.6V

- Lpri = 15uH
 - Nturns = Npri / Nsec = 0.8
 - Nturns = Npri / Ndrive = 0.7
 - Nturns = Npri / Nbias = 0.62

3.9V @ 1.5A

NOTES:
 - DNP = "DO NOT POPULATE"
 - built on PMP30197_RevA

Orderable:	Designed for:	Mod. Date: 6/22/2017
TID #: N/A	Project File: inverting buck-boost flyback	
Number: PMP30197 Rev: B	Sheet Title:	
Assembly Variant: Version control disabled	Assembly Variant [No Variations]	Sheet: 1 of 1
Drawn By:	File: PMP30197_RevB_SchDoc	Size: B
Engineer: F. Mueller	Contact: http://www.ti.com/support	http://www.ti.com

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